

## CHIP SCHOTTKY BARRIER DIODES

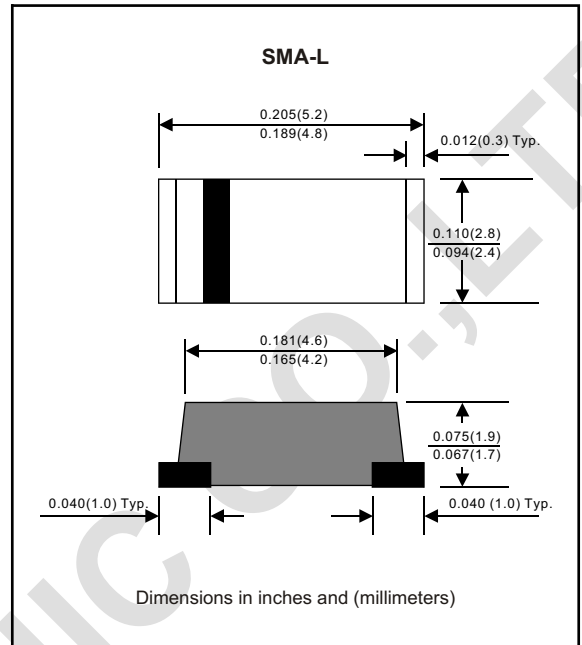
Glass passivated type

### FEATURES

- Plastic package gas Underwriters Laboratory Flammability Classification 94V-O Utilizing Flame Retardant Epoxy Molding Compound.
- For surfact mounted applications.
- Exceeds environmental standards of MIL-S-19500/228
- Low leakage current.

### MECHANICAL DATA

- **Case:** Molded plastic, JEDEC DO-241AC
- **Terminals:** Solder plates, solderable per MIL-STD-750 Method 2026
- **Polarity:** Indicated by cathode end
- **Mounting position:** Any
- **Weight:** 0.0015 ounce, 0.05 gram



MAXIMUM RATINGS (AT T<sub>A</sub>= 25°C unless otherwise note)

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNITS
Forward rectified current	Lead temperature = 90°C	I <sub>o</sub>			1.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I <sub>FSM</sub>			25	A
Reverse current	V <sub>R</sub> = V <sub>RRM</sub> T <sub>A</sub> = 25°C	I <sub>R</sub>			0.5	mA
	V <sub>R</sub> = V <sub>RRM</sub> T <sub>A</sub> = 125°C				10	mA
Thermal resistance	Junction to ambient	R <sub>θJA</sub>			95	°C/W
Diode junction capacitance	F = 1MHz and applied 4vDC reverse voltage	C <sub>J</sub>		15		pF
Operating temperature		T <sub>J</sub>	-55		+150	°C

SYMBOL	MARKING CODE	V <sub>RRM</sub> <sup>*1</sup> (v)	V <sub>RMS</sub> <sup>*2</sup> (v)	V <sub>R</sub> <sup>*3</sup> (v)	V <sub>F</sub> <sup>*4</sup> (v)	Storage temperature (°C)
FM5817	SK12	20	14	20	0.45	-55 to +150
FM5818	SK13	30	21	30	0.55	
FM5819	SK14	40	28	40	0.60	

\*1 Repetitive peak reverse voltage

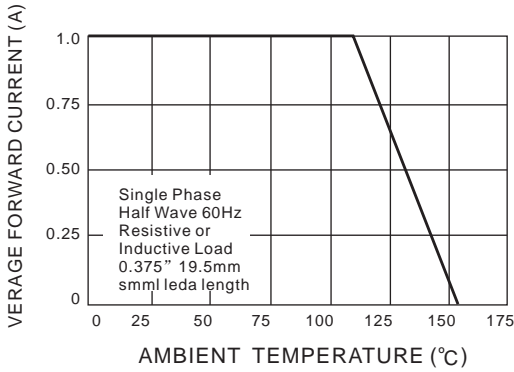
\*2 RMS voltage

\*3 Continuous reverse voltage

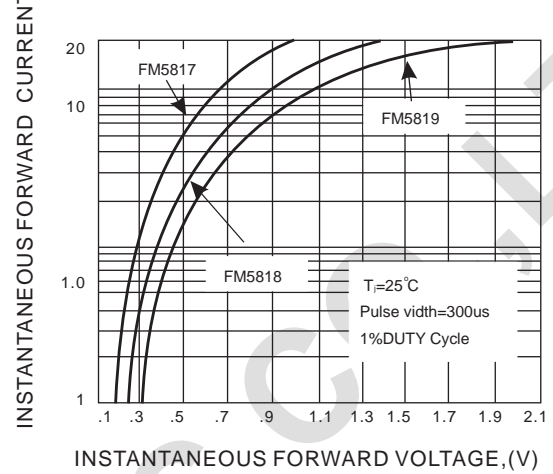
\*4 Forward rectified current

## RATING AND CHARACTERISTIC CURVES

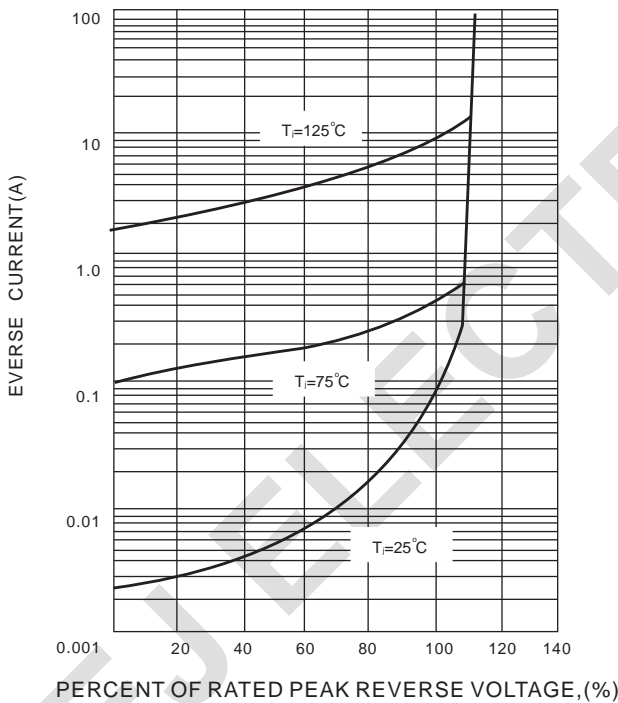
**FIG.1 TYPICAL FORWARD CURRENT DERATING CURVE**



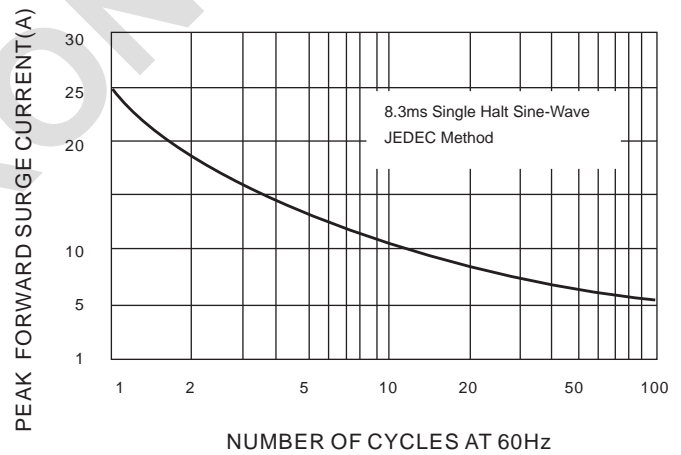
**FIG.2 TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS**



**FIG.3 TYPICAL REVERSE CHARACTERISTICS**



**FIG.4 -MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**



**FIG.5 TYPICAL JUNCTION CAPACITANCE**

